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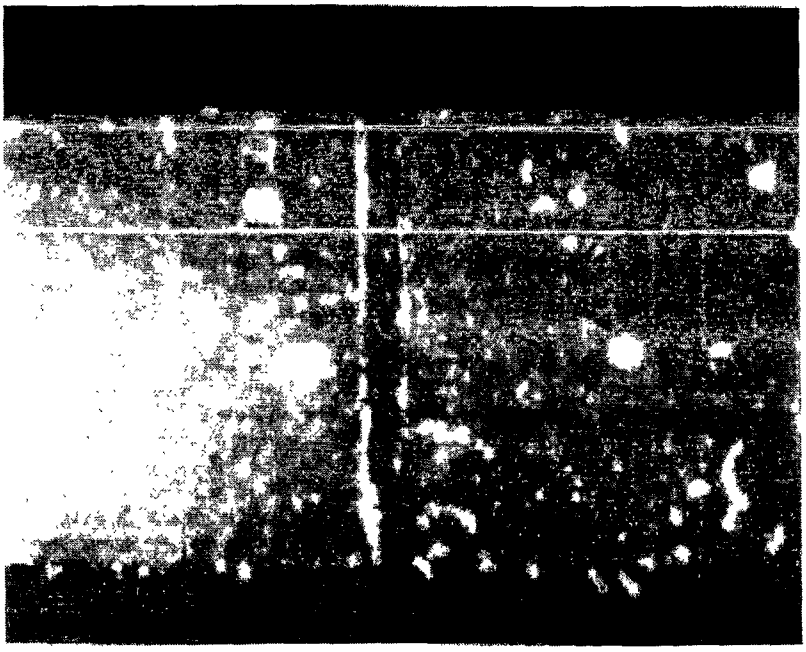
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(54) Title: CHEMICAL MECHANICAL POLISHING PAD WITH MICRO-HOLES



(57) Abstract: Disclosed is a chemical mechanical polishing pad formed at a polishing surface thereof with micro-holes each having a desired cross-sectional area while having a desired depth. The shape, size, and density of the micro-holes can be optionally adjusted. The chemical mechanical polishing pad provides an effect of maintaining a desired polishing rate during a polishing process. In accordance with the present invention, the micro-holes can have diverse arrangements depending on given process conditions.

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